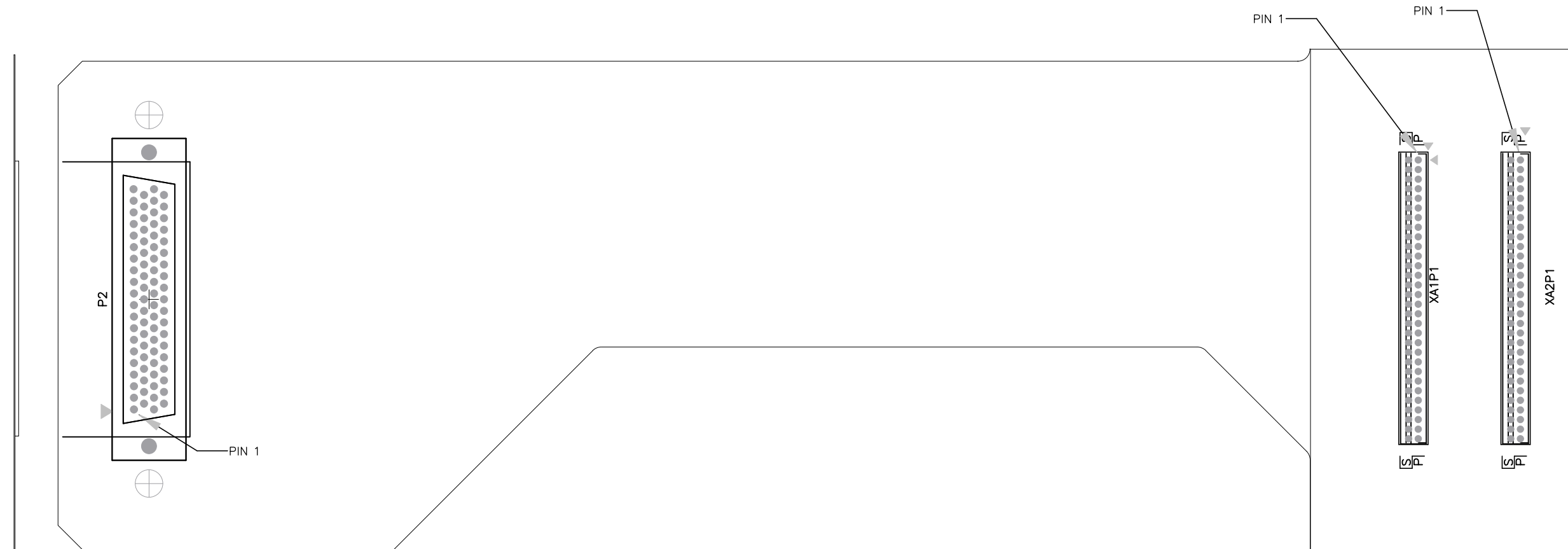


NOTES:

1. Bake per manufacturer instructions lower left corner of this document.
2. Connectors are mounted on the rigid side of circuit.
3. Solder using \_\_\_\_\_ lead free solder.
4. Support areas where connectors mount to ensure flatness and seating planes are flush.
5. To ensure proper alignment and engagement of the DB connector pins, have mating connector attached during soldering.

REVISIONS

ZONE	LTR	DESCRIPTION	ECR	DATE	BY	APRV
	A	Change shape to accomodate gigE module hardware		13JAN11	DMS	



## ASSEMBLY STIFFENER SIDE

**MANUFACTURER BAKING INSTRUCTIONS  
CIREXX**

Prior to any thermal exposure please follow the recommendations below for all flex and rigid flex circuit boards.

Bake all multilayer boards to high temperature exposure associated with any soldering process, boards are generally baked at 250 (120 C) for three to ten hours, depending on the board thickness and layer count.

Please follow suggested baking guideline listed below:

- <30 mils, bake for 3 hours
- 30-60 mils, bake for 4 hours
- 60-90 mils, bake for 6 hours
- >120 mils, bake for 10 hours

Baking removes any moisture that has absorbed from the atmosphere as well as during processing. Polyimide films absorb moisture quickly, therefore soldering, wave, IR or vapor phase should be done within 30 minutes after baking. Otherwise, store board in a dry box or sealed plastic bag until ready for soldering.

Vacuum ovens are also used to remove water. Lower temperatures 150-175 (65-80 C) can be used. This method also prevents the amount of oxidation of expose copper pads.

QTY REQ'D	PART OR IDENTIFYING NO	ITEM DESCRIPTION	ITEM NO
2	LS2-130-01-L-D	Con, straight 60 pin 2 mm trml/sckt combo XA1P1, XA2P1	3
1	DD78M30000-759.1	Con, DB78 male straight pcb mnt .150 with float bushings P2	2
1	TRNT-EL-04-1006	FLEX CIRCUIT BLANK	1

TOLERANCES UNLESS OTHERWISE NOTED

.XX ± .03      ANGULAR ±.5°

.XXX ± .010

THIRD ANGLE PROJECTION

**NATIONAL OPTICAL ASTRONOMY OBSERVATORIES**  
OPERATED BY THE  
ASSOCIATION OF UNIVERSITIES FOR RESEARCH IN ASTRONOMY  
UNDER COOPERATIVE AGREEMENT WITH  
NATIONAL SCIENCE FOUNDATION

<b>DO NOT SCALE DRAWING</b>		NAME <b>ASSEMBLY DRAWING</b>	USED ON <b>TORRENT</b>	REF <b>A</b>
NEXT ASSEMBLY <b>TRNT-EL-02-0001</b>		DWG SIZE <b>C</b>		REV <b>A</b>
REFER TO SCHEMATIC <b>TRNT-EL-04-2006</b>		DWG NO <b>TRNT-EL-04-0006</b>		
SCALE: FULL	DESIGNED BY Dee Stover	DATE 15sep09	CHECKED BY	DATE
DWG PRODUCED USING PCAD 2006	DRAWN BY Dee Stover	DATE 15sep09	APPROVED BY	DATE
		RELEASED		SHEET 1 OF 1